SEMiX291D16s

SEMiX® 13

SEMiX291D16s

Features

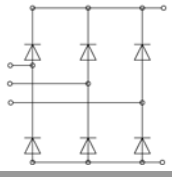
- Terminal height 17 mm
- Chips soldered directly to isolated substrate
- UL recognised file no. E63532

Typical Applications*

- Input Bridge Rectifier for AC/DC motor control
- Power supply

Absolute Maximum Ratings				
Symbol	**Conditions**		**Values**	**Unit**
Recitifier Diode				
I_D	T_j = 150 °C sinus 180°	T_c = 85 °C	232	A
		T_c = 100 °C	196	A
I_{FSM}	10 ms	T_j = 25 °C	1600	A
		T_j = 130 °C	1380	A
i^2t	10 ms	T_j = 25 °C	12800	A^2s
		T_j = 130 °C	9522	A^2s
V_{RSM}			1700	V
V_{RRM}			1600	V
T_j			-40 ... 150	°C
Module				
T_{stg}			-40 ... 125	°C
V_{isol}	AC sinus 50Hz	1 min	4000	V
		1 s	4800	V

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Diode						
V_F	T_j = 25 °C, I_F = 231 A				2.06	V
$V_{(TO)}$	T_j = 130 °C				0.83	V
r_T	T_j = 130 °C				4.6	mΩ
I_{RD}	T_j = 130 °C, V_{RD} = V_{RRM}				1.1	mA
$R_{th(j-c)}$	sin. 180	per diode			0.45	K/W
						K/W
Module						
$R_{th(c-s)}$	per chip					K/W
	per module			0.04		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t	to terminals (M6)		2.5		5	Nm
a					5 * 9,81	m/s^2
w					350	g



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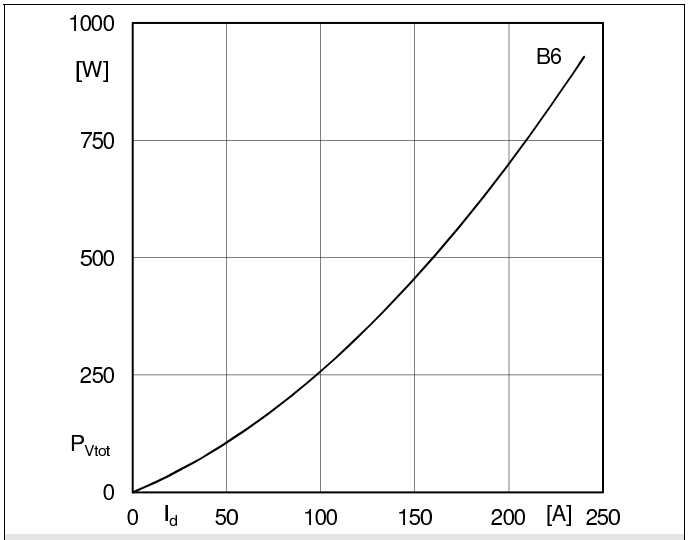


Fig. 4L: Power dissipation per module vs. direct current

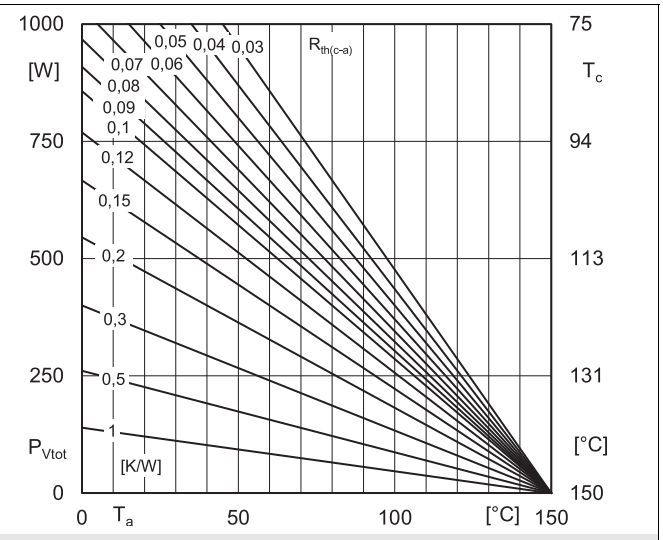


Fig. 4R: Power dissipation per module vs. case temperature

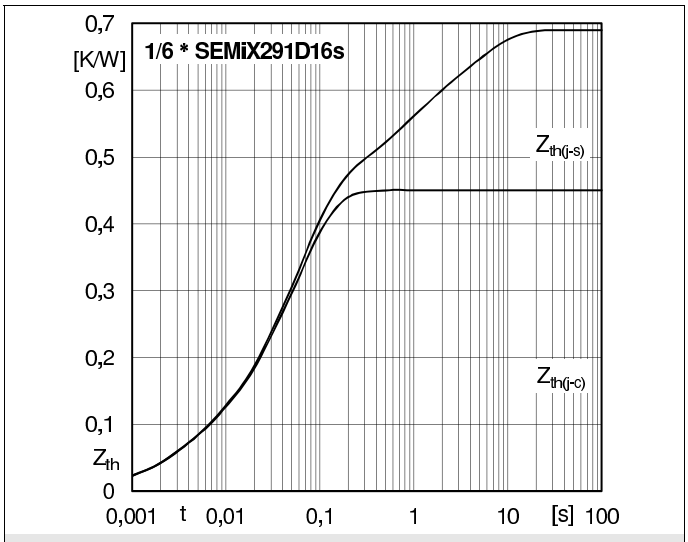


Fig. 6: Transient thermal impedance vs. time

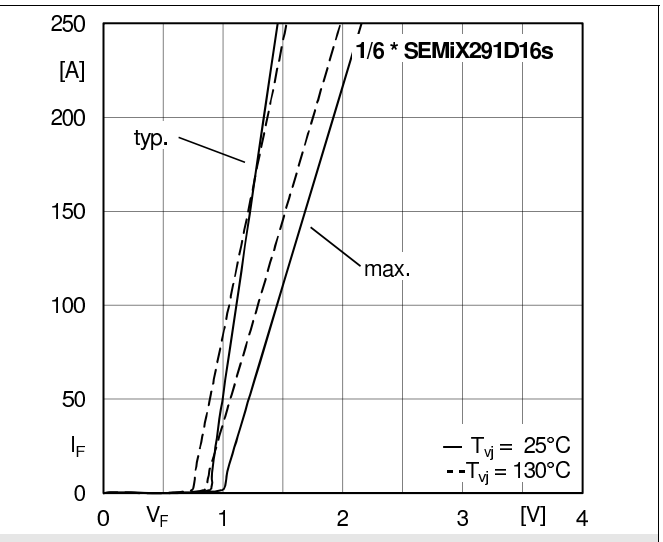


Fig. 7: On-state characteristics

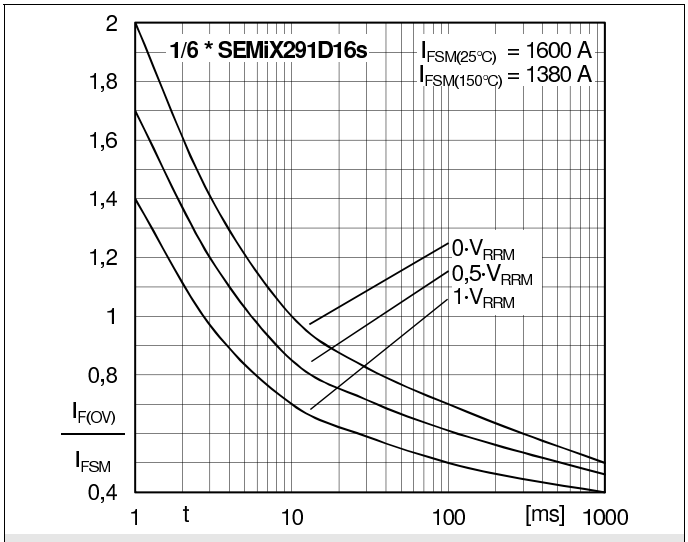
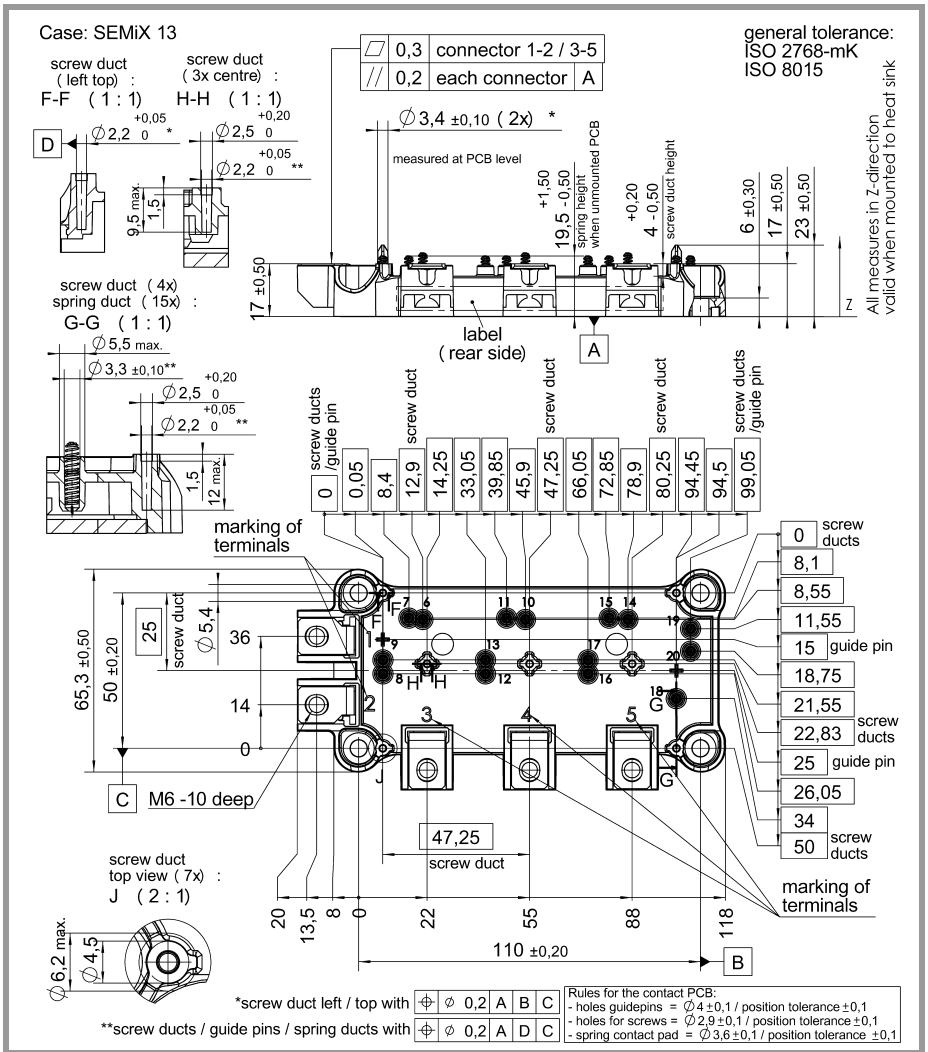


Fig. 8: Surge overload current vs. time



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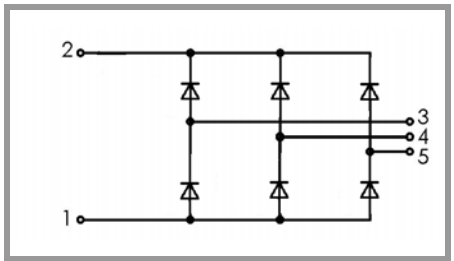

spring configuration

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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